

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2704cgw-16#trpbf

(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.778352**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.025475	1000000	32729.4101562		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.275671	975000	354172.71875		
		Iron (Fe)	7439-89-6	0.006786	24000	8718.421875		
		Phosphorus (P)	7723-14-0	0.000085	300	109.205101013		
		Zinc (Zn)	7440-66-6	0.000198	700	254.383636475		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.282740</b>	<b>1000000</b>	<b>363254.71875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012932	1000000	16614.4921875		
		<b>External Plating Total:</b>				<b>0.012932</b>	<b>1000000</b>	<b>16614.4921875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.002260	1000000	2903.57080078		
<b>Internal Plating Total:</b>				<b>0.002260</b>	<b>1000000</b>	<b>2903.57080078</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.004602	750000	5912.49316406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.001534	250000	1970.83105469		
<b>Die Attach Total:</b>				<b>0.006136</b>	<b>1000000</b>	<b>7883.32421875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.060440	135000	77651.2578125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.385022	860000	494663.15625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.002239	5000	2876.59082031		
		<b>Encapsulation Total:</b>				<b>0.447701</b>	<b>1000000</b>	<b>575191</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001108	1000000	1423.52075195		
					<b>TOTAL MASS (g) :</b>	<b>0.778352</b>		